

74ALVT16374

16-bit edge-triggered D-type flip-flop; 3-state

Product data sheet

1. General description

The 74ALVT16374 is a high performance BiCMOS product designed for V_{CC} operation at 2.5 V or 3.3 V with I/O compatibility up to 5 V.

This device is a 16-bit edge-triggered D-type flip-flop featuring non-inverting 3-state outputs. The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CP), the Q outputs of the flip-flop take on the logic levels set up at the D inputs.

2. Features

- 16-bit edge-triggered flip-flop
- 5 V I/O compatible
- 3-state buffers
- Output capability: +64 mA and -32 mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5 V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion and extraction permitted
- Power-up reset
- Power-up 3-state
- No bus current loading when output is tied to 5 V bus
- Latch-up protection exceeds 500 mA per JESD78
- Electrostatic discharge protection:
 - ◆ MIL STD 883 method 3015: exceeds 2000 V
 - ◆ Machine model: exceeds 200 V

PHILIPS

3. Quick reference data

Table 1: Quick reference data

$T_{amb} = 25\text{ }^{\circ}\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5\text{ V}$						
t_{PLH}	propagation delay nCP to nQx	$C_L = 50\text{ pF}$	-	2.6	-	ns
t_{PHL}	propagation delay nCP to nQx	$C_L = 50\text{ pF}$	-	2.8	-	ns
C_i	input capacitance nCP and nOE	$V_I = 0\text{ V or }V_{CC}$	-	3	-	pF
C_o	output capacitance	outputs disabled; $V_O = 0\text{ V or }V_{CC}$	-	9	-	pF
I_{CC}	supply current	outputs disabled	-	40	-	μA
$V_{CC} = 3.3\text{ V}$						
t_{PLH}	propagation delay nCP to nQx	$C_L = 50\text{ pF}$	-	2.1	-	ns
t_{PHL}	propagation delay nCP to nQx	$C_L = 50\text{ pF}$	-	2.3	-	ns
C_i	input capacitance nCP and nOE	$V_I = 0\text{ V or }V_{CC}$	-	3	-	pF
C_o	output capacitance	outputs disabled; $V_O = 0\text{ V or }V_{CC}$	-	9	-	pF
I_{CC}	supply current	outputs disabled	-	40	-	μA

4. Ordering information

Table 2: Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ALVT16374DGG	-40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1
74ALVT16374DL	-40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1

7. Functional description

7.1 Function table

Table 4: Function table ^[1]

Input			Internal register	Output	Operating mode
nOE	nCP	nDx		nQx	
L	↑	l	L	L	load and read register
L	↑	h	H	H	
L	NC	X	NC	NC	hold
H	NC	X	NC	Z	disable outputs
H	↑	nDx	nDx	Z	

- [1] H = HIGH voltage level;
 h = HIGH voltage level one setup time prior to the HIGH-to-LOW clock transition;
 L = LOW voltage level;
 l = LOW voltage level one setup time prior to the HIGH-to-LOW clock transition;
 NC = no change;
 X = don't care;
 Z = high-impedance OFF-state;
 ↑ = LOW-to-HIGH clock transition.

8. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
V_I	input voltage		^[1] -0.5	+7.0	V
V_O	output voltage	output in OFF-state or HIGH-state	^[1] -0.5	+7.0	V
I_{IK}	input diode current	$V_I < 0$ V	-	-50	mA
I_{OK}	output diode current	$V_O < 0$ V	-	-50	mA
I_O	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-	-64	mA
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		^[2] -	150	°C

- [1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- [2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

9. Recommended operating conditions

Table 6: Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$						
V_{CC}	supply voltage		2.3	-	2.7	V
V_I	input voltage		0	-	5.5	V
V_{IH}	HIGH-level input voltage		1.7	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.7	V
I_{OH}	HIGH-level output current		-	-	-8	mA
I_{OL}	LOW-level output current	none	-	-	8	mA
		duty cycle < 50 %; $f \geq 1\text{ kHz}$	-	-	24	mA
$\Delta t/\Delta V$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature		-40	-	+85	°C
$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$						
V_{CC}	supply voltage		3.0	-	3.6	V
V_I	input voltage		0	-	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
I_{OH}	HIGH-level output current		-	-	-32	mA
I_{OL}	LOW-level output current	none	-	-	32	mA
		duty cycle < 50 %; $f \geq 1\text{ kHz}$	-	-	64	mA
$\Delta t/\Delta V$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature		-40	-	+85	°C

10. Static characteristics

Table 7: Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

$T_{amb} = -40\text{ °C to }+85\text{ °C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ [1]						
V_{IK}	input diode voltage	$V_{CC} = 2.3\text{ V}$; $I_{IK} = -18\text{ mA}$	-	-0.85	-1.2	V
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.3\text{ V to }3.6\text{ V}$; $I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$	V_{CC}	-	V
		$V_{CC} = 2.3\text{ V}$; $I_{OH} = -8\text{ mA}$	1.8	2.1	-	V
V_{OL}	LOW-level output voltage	$V_{CC} = 2.3\text{ V}$; $I_{OL} = 100\text{ }\mu\text{A}$	-	0.07	0.2	V
		$V_{CC} = 2.3\text{ V}$; $I_{OL} = 24\text{ mA}$	-	0.3	0.5	V
V_{RST}	power-up LOW-state output voltage	$V_{CC} = 2.7\text{ V}$; $I_O = 1\text{ mA}$; $V_I = V_{CC}$ or GND	[2] -	-	0.55	V

Table 7: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

 $T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit		
I_{LI}	input leakage current	control pins	$V_{CC} = 2.7\text{ V}; V_I = V_{CC}$ or GND	-	0.1	± 1	μA	
			$V_{CC} = 0\text{ V}$ or $2.7\text{ V}; V_I = 5.5\text{ V}$	-	0.1	10	μA	
	I/O data pins		$V_{CC} = 2.7\text{ V}; V_I = V_{CC}$	[3]	-	0.1	1	μA
			$V_{CC} = 2.7\text{ V}; V_I = 0\text{ V}$	[3]	-	+0.1	-5	μA
I_{OFF}	output power-down current	$V_{CC} = 0\text{ V}; V_I$ or $V_O = 0\text{ V}$ to 4.5 V	-	0.1	± 100	μA		
I_{HOLD}	bus hold current D inputs	$V_{CC} = 2.3\text{ V}; V_I = 0.7\text{ V}$	[4] [5]	-	90	-	μA	
		$V_{CC} = 2.3\text{ V}; V_I = 1.7\text{ V}$	[4] [5]	-	-10	-	μA	
I_{EX}	external current into output	output in HIGH-state when $V_O > V_{CC}; V_O = 5.5\text{ V}; V_{CC} = 2.3\text{ V}$	-	10	125	μA		
I_{PU}	power-up 3-state output current	$V_{CC} \leq 1.2\text{ V}; V_O = 0.5\text{ V}$ to $V_{CC}; V_I = \text{GND}$ or $V_{CC}; n\overline{OE} = \text{don't care}$	[6]	-	1	100	μA	
I_{PD}	power-down 3-state output current	$V_{CC} \leq 1.2\text{ V}; V_O = 0.5\text{ V}$ to $V_{CC}; V_I = \text{GND}$ or $V_{CC}; n\overline{OE} = \text{don't care}$	[6]	-	1	100	μA	
I_{OZ}	3-state OFF-state output current	$V_{CC} = 2.7\text{ V}; V_I = V_{IH}$ or V_{IL}						
		output HIGH; $V_O = 2.3\text{ V}$	-	0.5	5	μA		
		output LOW; $V_O = 0.5\text{ V}$	-	+0.5	-5	μA		
I_{CC}	supply current	$V_{CC} = 2.7\text{ V}; V_I = V_{CC}$ or GND; $I_O = 0\text{ A}$						
		outputs HIGH-state	-	0.04	0.1	mA		
		outputs LOW-state	-	2.7	4.5	mA		
		outputs disabled	[7]	-	0.04	0.1	mA	
ΔI_{CC}	additional supply current per input pin	$V_{CC} = 2.3\text{ V}$ to $2.7\text{ V};$ one input at $V_{CC} - 0.6\text{ V};$ other inputs at V_{CC} or GND	[8]	-	0.04	0.4	mA	
C_i	input capacitance nCP and nOE	$V_I = 0\text{ V}$ or V_{CC}	-	3	-	pF		
C_o	output capacitance	outputs disabled; $V_O = 0\text{ V}$ or V_{CC}	-	9	-	pF		
$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ [9]								
V_{IK}	input clamp voltage	$V_{CC} = 3.0\text{ V}; I_{IK} = -18\text{ mA}$	-	-0.85	-1.2	V		
V_{OH}	HIGH-level output voltage	$V_{CC} = 3.0\text{ V}$ to $3.6\text{ V}; I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$	V_{CC}	-	V		
		$V_{CC} = 3.0\text{ V}; I_{OH} = -32\text{ mA}$	2.0	2.3	-	V		
V_{OL}	LOW-level output voltage	$V_{CC} = 3.0\text{ V}; I_{OL} = 100\text{ }\mu\text{A}$	-	0.07	0.2	V		
		$V_{CC} = 3.0\text{ V}; I_{OL} = 16\text{ mA}$	-	0.25	0.4	V		
		$V_{CC} = 3.0\text{ V}; I_{OL} = 32\text{ mA}$	-	0.3	0.5	V		
		$V_{CC} = 3.0\text{ V}; I_{OL} = 64\text{ mA}$	-	0.4	0.55	V		
V_{RST}	power-up LOW-state output voltage	$V_{CC} = 3.6\text{ V}; I_O = 1\text{ mA}; V_I = V_{CC}$ or GND	[2]	-	0.55	V		

Table 7: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

 $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
I_{LI}	input leakage current	control pins					
		$V_{CC} = 3.6\text{ V}$; $V_I = V_{CC}$ or GND	-	0.1	± 1	μA	
		$V_{CC} = 0\text{ V}$ or 3.6 V ; $V_I = 5.5\text{ V}$	-	0.1	10	μA	
	I/O data pins	$V_{CC} = 3.6\text{ V}$; $V_I = V_{CC}$	[3]	-	0.1	1	μA
$V_{CC} = 3.6\text{ V}$; $V_I = 0\text{ V}$		[3]	-	0.1	-5	μA	
I_{OFF}	output power-down current	$V_{CC} = 0\text{ V}$; V_I or $V_O = 0\text{ V}$ to 4.5 V	-	0.1	± 100	μA	
I_{HOLD}	bus hold current D inputs	$V_{CC} = 3.0\text{ V}$; $V_I = 0.8\text{ V}$	[5]	75	130	-	μA
		$V_{CC} = 3.0\text{ V}$; $V_I = 2.0\text{ V}$	[5]	-75	-140	-	μA
		$V_{CC} = 0\text{ V}$ to 3.6 V ; $V_I = 3.6\text{ V}$	[5]	± 500	-	-	μA
I_{EX}	external current into output	output in HIGH-state when $V_O > V_{CC}$; $V_O = 5.5\text{ V}$; $V_{CC} = 3.0\text{ V}$	-	10	125	μA	
I_{PU}	power-up 3-state output current	$V_{CC} \leq 1.2\text{ V}$; $V_O = 0.5\text{ V}$ to V_{CC} ; $V_I = V_{CC}$ or GND; $nOE = \text{don't care}$	[10]	-	1	± 100	μA
I_{PD}	power-down 3-state output current	$V_{CC} \leq 1.2\text{ V}$; $V_O = 0.5\text{ V}$ to V_{CC} ; $V_I = V_{CC}$ or GND; $nOE = \text{don't care}$	[10]	-	1	± 100	μA
I_{OZ}	3-state OFF-state output current	$V_{CC} = 3.6\text{ V}$; $V_I = V_{IH}$ or V_{IL}					
		output HIGH; $V_O = 3.0\text{ V}$	-	0.5	5	μA	
		output LOW; $V_O = 0.5\text{ V}$	-	+0.5	-5	μA	
I_{CC}	supply current	$V_{CC} = 3.6\text{ V}$; $V_I = \text{GND}$ or V_{CC} ; $I_O = 0\text{ A}$					
		outputs HIGH-state	-	0.04	0.1	mA	
		outputs LOW-state	-	3.7	6	mA	
		outputs disabled	[7]	-	0.04	0.1	mA
ΔI_{CC}	additional supply current per input pin	$V_{CC} = 3.0\text{ V}$ to 3.6 V ; one input at $V_{CC} - 0.6\text{ V}$; other inputs at V_{CC} or GND	[8]	-	0.04	0.4	mA
C_i	input capacitance nCP and nOE	$V_I = 0\text{ V}$ or V_{CC}	-	3	-	pF	
C_o	output capacitance	outputs disabled; $V_O = 0\text{ V}$ or V_{CC}	-	9	-	pF	

[1] Typical values are at $V_{CC} = 2.5\text{ V}$ and $T_{amb} = 25\text{ }^{\circ}\text{C}$.

[2] For valid test results, data must not be loaded into the flip-flops (or latches) after applying power.

[3] Unused pins at V_{CC} or GND.

[4] Not guaranteed

[5] This is the bus-hold overdrive current required to force the input to the opposite logic state.

[6] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms . From $V_{CC} = 1.2\text{ V}$ to $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ a transition time of $100\text{ }\mu\text{s}$ is permitted. This parameter is valid for $T_{amb} = 25\text{ }^{\circ}\text{C}$ only.[7] I_{CC} is measured with outputs pulled to V_{CC} or GND.[8] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.[9] Typical values are at $V_{CC} = 3.3\text{ V}$ and $T_{amb} = 25\text{ }^{\circ}\text{C}$.[10] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms . From $V_{CC} = 1.2\text{ V}$ to $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ a transition time of $100\text{ }\mu\text{s}$ is permitted. This parameter is valid for $T_{amb} = 25\text{ }^{\circ}\text{C}$ only.

11. Dynamic characteristics

Table 8: Dynamic characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; $GND = 0\text{ V}$; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ [1]						
f_{max}	maximum clock frequency	see Figure 5	150	-	-	MHz
t_{PLH}	propagation delay nCP to nQx	see Figure 5	1.5	2.6	4.2	ns
t_{PHL}	propagation delay nCP to nQx	see Figure 5	1.5	2.8	4.5	ns
t_{PZH}	output enable time to HIGH-level	see Figure 6	1.0	3.4	5.6	ns
t_{PZL}	output enable time to LOW-level	see Figure 7	1.0	2.6	4.7	ns
t_{PHZ}	output disable time from HIGH-level	see Figure 6	2.0	2.7	4.4	ns
t_{PLZ}	output disable time from LOW-level	see Figure 7	1.0	2.0	3.3	ns
$t_{su(H)}$	setup time HIGH nDx to nCP	see Figure 8	1.0	0	-	ns
$t_{su(L)}$	setup time LOW nDx to nCP	see Figure 8	1.5	0.4	-	ns
$t_{h(H)}$	hold time HIGH nDx to nCP	see Figure 8	0.5	0	-	ns
$t_{h(L)}$	hold time LOW nDx to nCP	see Figure 8	0.5	0	-	ns
t_{WH}	nCP pulse width HIGH	see Figure 5	1.5	-	-	ns
t_{WL}	nCP pulse width LOW	see Figure 5	1.5	-	-	ns
$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ [2]						
f_{max}	maximum clock frequency	see Figure 5	250	-	-	MHz
t_{PLH}	propagation delay nCP to nQx	see Figure 5	1.0	2.1	3.2	ns
t_{PHL}	propagation delay nCP to nQx	see Figure 5	1.0	2.3	3.2	ns
t_{PZH}	output enable time to HIGH-level	see Figure 6	1.0	2.3	3.8	ns
t_{PZL}	output enable time to LOW-level	see Figure 7	1.0	2.0	3.2	ns
t_{PHZ}	output disable time from HIGH-level	see Figure 6	1.0	2.7	4.2	ns
t_{PLZ}	output disable time from LOW-level	see Figure 7	1.0	2.6	3.6	ns
$t_{su(H)}$	setup time HIGH nDx to nCP	see Figure 8	1.0	0	-	ns
$t_{su(L)}$	setup time LOW nDx to nCP	see Figure 8	1.5	0	-	ns
$t_{h(H)}$	hold time HIGH nDx to nCP	see Figure 8	0.5	0	-	ns
$t_{h(L)}$	hold time LOW nDx to nCP	see Figure 8	0.5	0	-	ns
t_{WH}	nCP pulse width HIGH	see Figure 5	1.5	-	-	ns
t_{WL}	nCP pulse width LOW	see Figure 5	1.5	-	-	ns

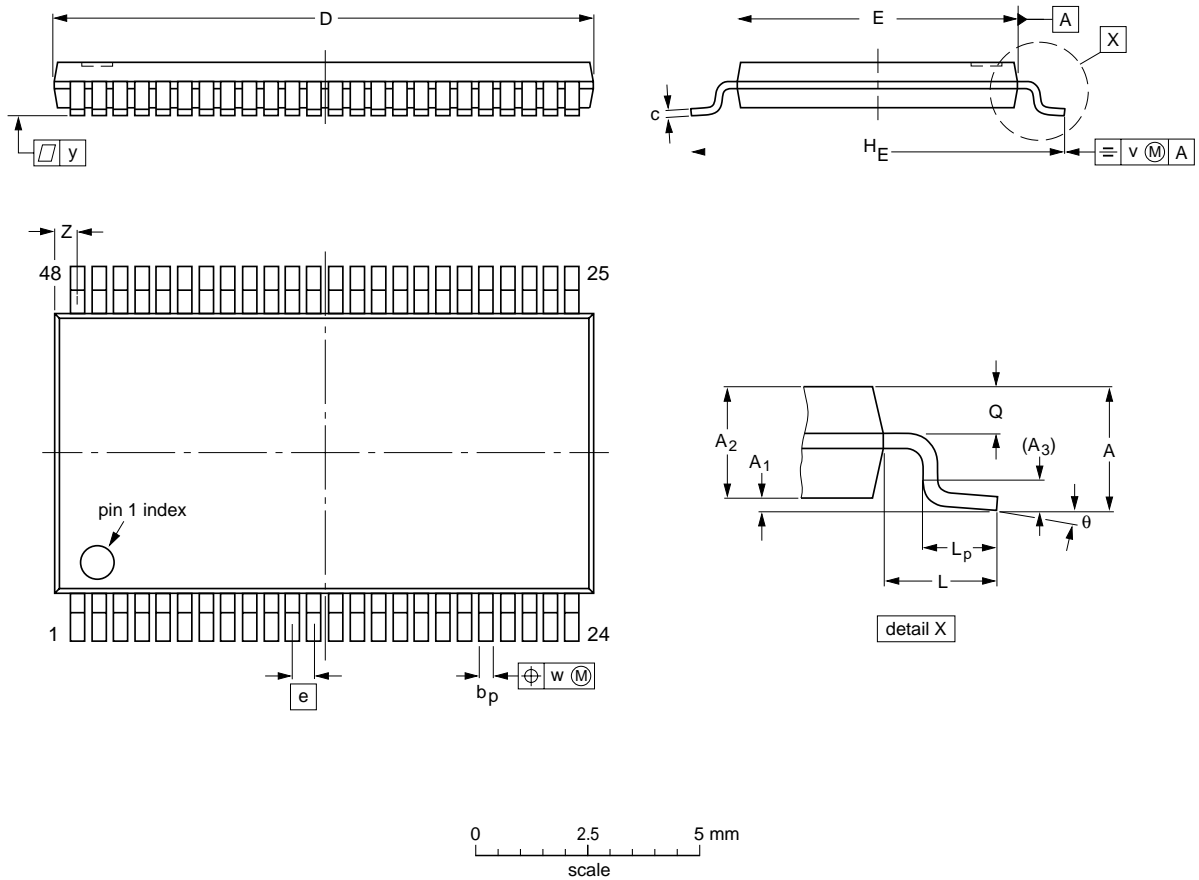
[1] Typical values are at $V_{CC} = 2.5\text{ V}$ and $T_{amb} = 25\text{ }^{\circ}\text{C}$.

[2] Typical values are at $V_{CC} = 3.3\text{ V}$ and $T_{amb} = 25\text{ }^{\circ}\text{C}$.

13. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION
	IEC	JEDEC	JEITA		
SOT362-1		MO-153			

Fig 10. Package outline SOT362-1 (TSSOP48)